

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			
INFORMATION DISCLOSURE STATEMENT		Docket Number: 10191/4346	
Application Number <b>To Be Assigned</b>	Filing Date <b>Herewith</b>	Examiner	Art Unit
Invention Title <b>METHOD FOR PRODUCING ETCHED HOLES AND/OR ETCHED TRENCHES AS WELL AS A DIAPHRAGM SENSOR UNIT</b>		Inventor(s) <b>Joachim RUDHARD</b>	

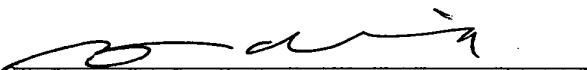
Address to:

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

- I. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 37 C.F.R. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorney for Applicant hereby brings the following references to the attention of the Examiner. The references are listed on the attached modified PTO Form No. 1449. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that these references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.
- II. A copy of each patent, publication or other information listed on the modified PTO form 1449 is enclosed, except as otherwise indicated on the modified PTO form 1449.

Dated: **3/8/06**

By:



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INFORMATION DISCLOSURE STATEMENT BY APPLICANT PTO FORM 1449	Atty. Docket No. 10191/4346	Serial No. To Be Assigned <b>10/571246</b>
	Applicant(s) Joachim RUDHARD	
	Filing Date Herewith	Group To Be Assigned

**U. S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,198,098*	March 6, 2001	Laou			
	6,210,988*	April 3, 2001	Franke et al.			

**FOREIGN PATENT DOCUMENTS**

EXAMINER'S INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS**

EXAMINER'S INITIALS		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
		Tillack B. et al; MONITORING OF DEPOSITION AND DRY ETCHING OF Si/SiGe MULTIPLE STACKS; Journal of Vacuum Science And Technology: Part B, American Institute Of Physics, New York, US.*
		Premachandran C S et al; A NOVEL ELECTRICALLY CONDUCTIVE WAFER THROUGH HOLD FILLED VIAS INTERCONNECT FOR 3D MEMS PACKAGING; 2003 Proceedings 53 <sup>rd</sup> , Electronic Components And Technology Conference.*
EXAMINER		DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.		

\*Copy of reference is not enclosed because reference is cited in Search Report (copy of reference provided by International Searching Authority).